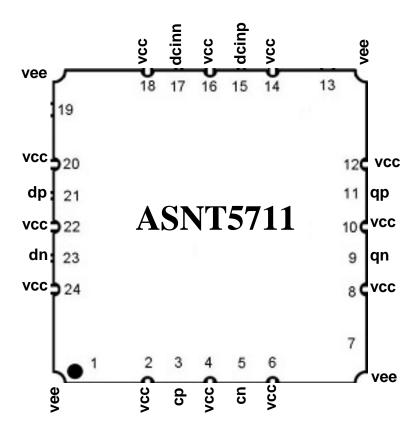
# ASNT5711-KHC DC-64Gbps D-Type Flip-Flop with Amplitude Adjust

- High speed broadband D-Type Flip-Flop for data retiming with full rate clock
- Input data common mode control
- 2ps set-up/hold time capability
- 88% clock phase margin for retiming of data input eye
- Fully differential CML input interfaces
- Fully differential CML output interface
- Single +3.3V or -3.3V power supply
- Power consumption: 530*mW*
- Exhibits low jitter and limited temperature variation over industrial temperature range
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFN 24-pin package



#### DESCRIPTION

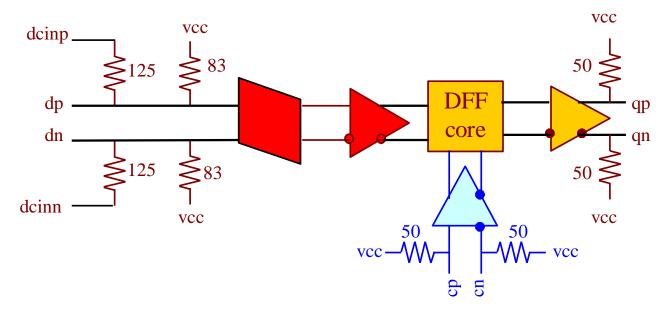


Fig. 1. Functional Block Diagram

The temperature stable ASNT5711-KHC SiGe IC provides broadband data retiming functionality and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can sample a high-speed data signal dp/dn with a full-rate external clock cp/cn to create a full-rate retimed NRZ data output qp/qn. The internal DC common mode voltage levels on data inputs dp/dn can be adjusted by applying analog voltages to the control ports dcinp/dcinn.

The part's I/O's support the CML logic interface with on chip equivalent 50*Ohms* termination and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION).

# **HS Clock Input Buffer**

The buffer can accept high-speed signals at its differential CML input port cp/cn. It can also accept a single-ended signal with a threshold voltage applied to the unused pin. It can handle a wide range of input signal amplitudes. The buffer utilizes on-chip single-ended 50*Ohms* termination to vcc for each input line.

### **HS Data Input Buffer**

The buffer can accept high-speed signals at its differential CML input port dp/dn. It can also accept a single-ended signal with a threshold voltage applied to the unused pin. It can handle a wide range of input signal amplitudes. The buffer utilizes on-chip single-ended 50*Ohms* termination to vcc for each input line.

The buffer allows for adjustment of DC common-mode voltage levels of input ports dp/dn by manipulating voltages applied to the control ports dcinp/dcinn, respectively. For correct input internal



termination, the ports dcinp/dcinn should be always connected to a power supply source, e.g. vcc if no shifts are required.

## **HS Data Output Buffer**

The buffer receives high-speed serial data from the DFF core and converts it into a differential CML output signal qp/qn. Each buffer utilizes internal single-ended 50*Ohm* loads to vcc and requires single-ended 50*Ohms* external termination. The termination resistors can be connected from each output directly to vcc, or through DC blocks to vee.

#### POWER SUPPLY CONFIGURATION

The part can operate with either a negative supply (vcc = 0.0V = ground and vee = -3.3V), or a positive supply (vcc = +3.3V and vee = 0.0V = ground). In case of a positive supply, all I/Os need AC termination when connected to any devices with 50Ohms termination to ground. Different PCB layouts will be needed for each different power supply combination.

#### All the characteristics detailed below assume vcc = 0.0V and vee = -3.3V.

#### ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground (assumed **vcc**).

**Parameter** Min **Units** Max Supply Voltage (vee) -3.6 **Power Consumption** W 0.60 Input Data Voltage Swing (SE) 1.0 VInput Clk Voltage Swing (SE) 1.0 VCase Temperature +90 ${}^{o}C$ Storage Temperature -40 +100 ${}^{o}C$ **Operational Humidity** 98 10 % Storage Humidity 98 10 %

Table 1. Absolute Maximum Ratings

#### TERMINAL FUNCTIONS

TERMINAL			Pin	Default	Termination	
Name	No.	Type	function	state		
High-Speed I/Os						
dp	21	CML	Input data		SE 83 <i>Ohms</i> to vcc and	
dn	23	Input	_		125 <i>Ohms</i> to dcinp/n respect.	
ср	3	CML	Input clock		SE 50 <i>Ohms</i> to <b>vcc</b>	



TERMINAL			Pin		Default	Termination		
Name	No.	Type	fun	ction	state			
cn	5	Input						
qp	11	CML	Output da	ta.		SE 50 <i>Ohms</i> to vcc. Require		
qn	9	Output				external SE 50 <i>Ohms</i> to <b>vcc</b>		
DC Controls								
dcinp	15	Analog	Input data	common	Connect	125 <i>Ohms</i> to corresponding		
dcinn	17	voltage	mode volta	age control	to vcc!	inputs		
	Supply and Termination Voltages							
Name	Description			Pin Number				
vcc	Pos	itive power supply		2, 4, 6, 8, 10, 12, 14, 16, 18, 20, 22, 24				
		(+3.3V  or  0V)						
vee	Neg	ative pow	er supply	1, 7, 13, 19				
		(0V  or  -3)	3.3 <i>V</i> )					

### **ELECTRICAL CHARACTERISTICS**

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS		
General Parameters							
VCC		0.0		V	External ground		
vee	-3.1	-3.3	-3.5	V	±6%		
Ivcc		160	182	mA			
Power consumption		530	600	mW			
Junction temperature	-25	50	125	$^{\circ}C$			
		HS	S Input Data	(dp/dn)			
Data rate	DC		64	Gbps			
Swing	0.05		0.80	V	Differential or SE, p-p		
CM Voltage Level	vcc-0.7+sv	v/2 vc	c+0.6-sw/2	V	Must match for both inputs		
		HS	Input Clock	k (cp/cn)			
Frequency	DC		64	GHz			
Swing	0.05		0.8	V	Differential or SE, p-p		
CM Voltage Level	vcc-0.7	V	cc+0.6-sw/2	V	Must match for both inputs		
Duty Cycle	40	50	60	%			
Clock phase margin	86	88	90	%	For reliable data latching		
		HS	<b>Output Data</b>	a (qp/qn	)		
Data rate	DC		64	Gbps			
Jitter		TBD		ps	Peak-to-peak at 64 Gbps		
DC Input Controls (cdinp, cdinn)							
Max level		vcc		$\overline{V}$			
Min level	,	vcc - 1.:	3	V			



#### PACKAGE INFORMATION

The die is housed in a custom 24-pin CQFN package shown in Fig. 2. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section be soldered to the VCC plain, which is ground for a negative supply, or power for a positive supply.

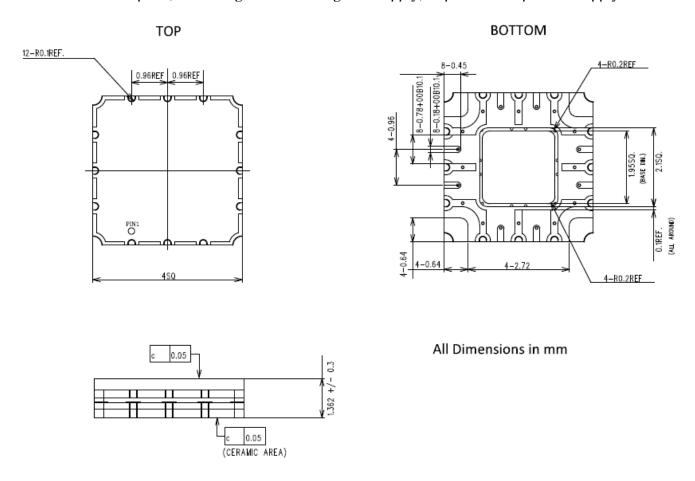


Fig. 2. CQFN 24-Pin Package Drawing (All Dimensions in mm)

The part's identification label is ASNT5711-KHC. The first 8 characters of the name before the underscore identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the underscore represent the package's manufacturer, type, and pin out count.

This device complies with Commission Delegated Directive (EU) 2015/863 of 4 June 2015 amending Annex II to Directive 2011/65/EU of the European Parliament and of the Council as regards the list of restricted substances (Text with EEA relevance) on the restriction of the use of certain hazardous substances in electrical and electronics equipment (RoHS Directive) in accordance with the definitions set forth in the directives for all ten substances.

Rev. 1.0.2 5 November 2023



Office: (310) 530-9400 Fax: (310) 530-9402

www.adsantec.com

## **REVISION HISTORY**

Revision	Date	Changes	
1.0.2	11-2023	First release	
0.0.1	04-2023	Preliminary release	